PHOTOCOUPLER

PS8501,PS8501L1,PS8501L2,PS8501L3

HIGH SPEED ANALOG OUTPUT TYPE 8 mm CREEPAGE 8-PIN PHOTOCOUPLER –NEPOC Series–

DESCRIPTION

The PS8501, PS8501L1, PS8501L2 and PS8501L3 are 8-pin high speed photocouplers containing a GaAlAs LED on input side and a PN photodiode and a high speed amplifier transistor on output side on one chip. The PS8501 is in a plastic DIP (Dual In-line Package) with 8 mm creepage distance product.

The PS8501L1 is lead bending type for long creepage distance.

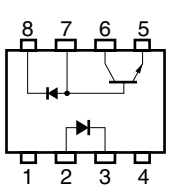
The PS8501L2 is lead bending type for long creepage distance (Gull-wing) for surface mount.

The PS8501L3 is lead bending type (Gull-wing) for surface mounting.

FEATURES

- Long creepage distance (8 mm MIN.: PS8501L1, PS8501L2)
- High supply voltage (V_{CC} = 35 V MAX.)
- High speed response (t_{PHL}, t_{PLH} = 0.8 μs MAX.)
- High isolation voltage (BV = 5 000 Vr.m.s.)
- TTL, CMOS compatible with a resistor
- Ordering number of tape product: PS8501L2-E3: 1 000 pcs/reel
  : PS8501L3-E3: 1 000 pcs/reel
- Pb-Free product
- Safety standards
  - UL approved: No. E72422
<R>
  - CSA approved: No. CA 101391 (CA5A, CAN/CSA-C22.2 60065, 60950)
  - BSI approved: No. 8937, 8938
  - SEMKO approved: No. 615433
  - NEMKO approved: No. P06207243
  - DEMKO approved: No. 314091
  - FIMKO approved: No. FI 22827
<R>
  - DIN EN60747-5-2 (VDE0884 Part2) approved: No. 40019182 (Option)

PIN CONNECTION
(Top View)



1. NC
2. Anode
3. Cathode
4. NC
5. Emitter
6. V_O
7. Base
8. V_{CC}

APPLICATIONS

- Interface for measurement or control equipment
- Substitutions for relays and pulse transformers
- Modem, communications device
- General purpose inverter

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Document No. PN10656EJ04V0DS (4th edition)
Date Published September 2009 NS
Printed in Japan

The mark <R> shows major revised points.

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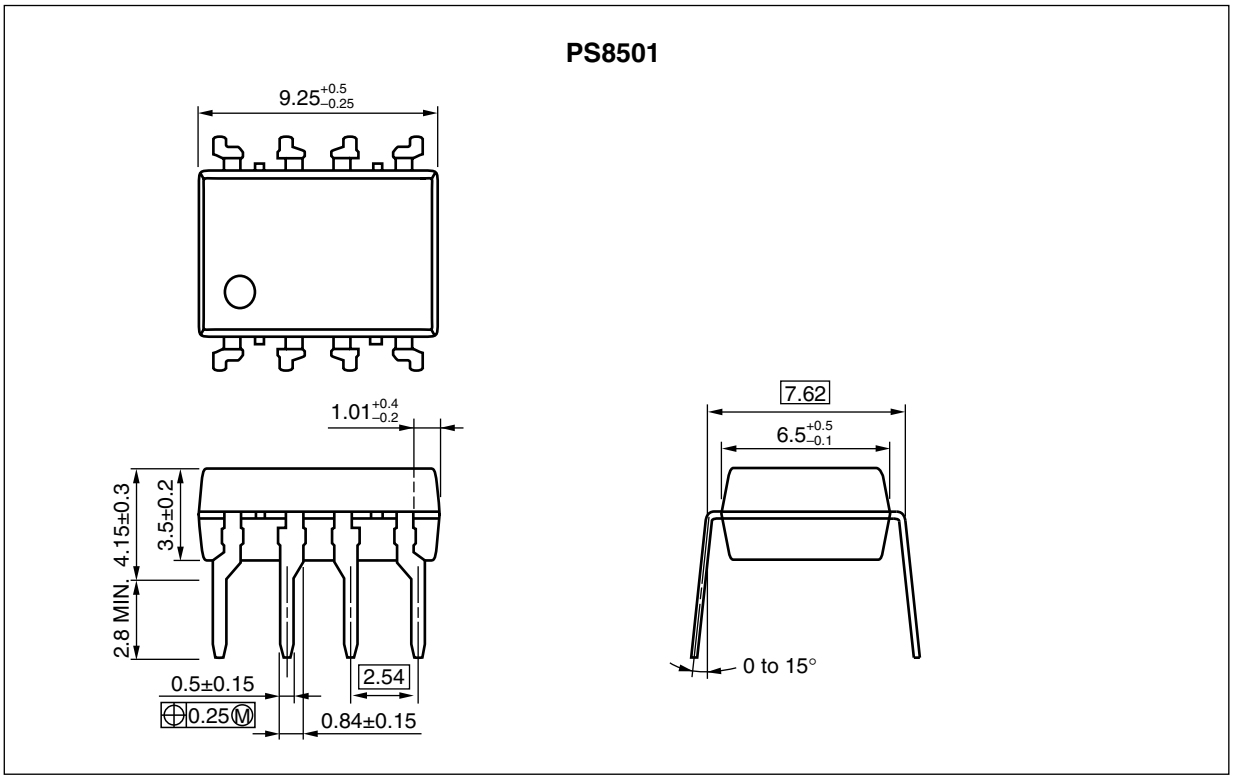
The revised points can be easily searched by copying an "<R>" in the PDF file and specifying it in the "Find what:" field.

<R> **PACKAGE DIMENSIONS (UNIT: mm)**

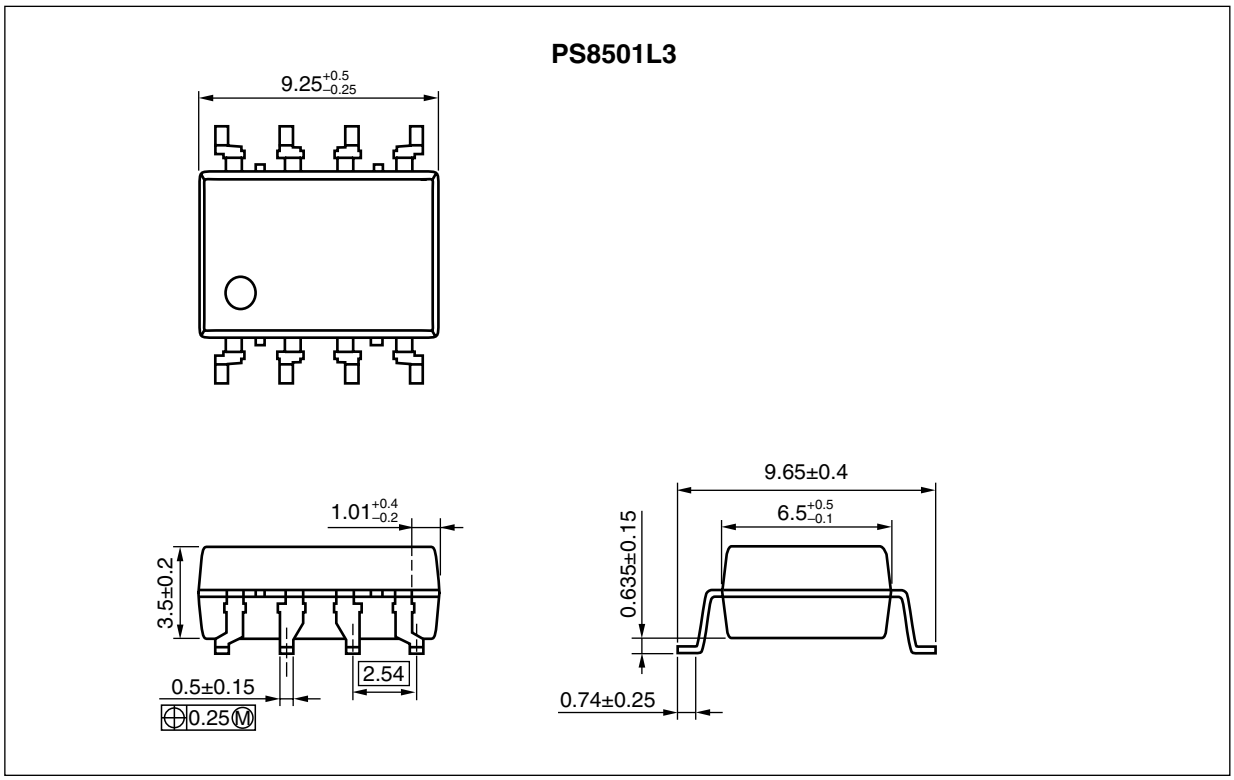
DIP Type

PS8501



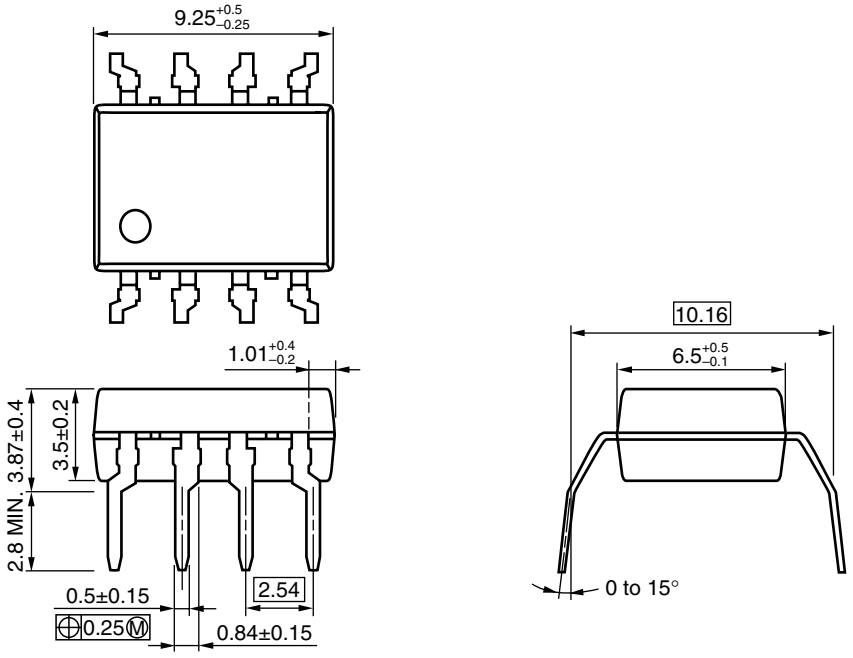
Lead Bending Type (Gull-wing) For Surface Mount

PS8501L3



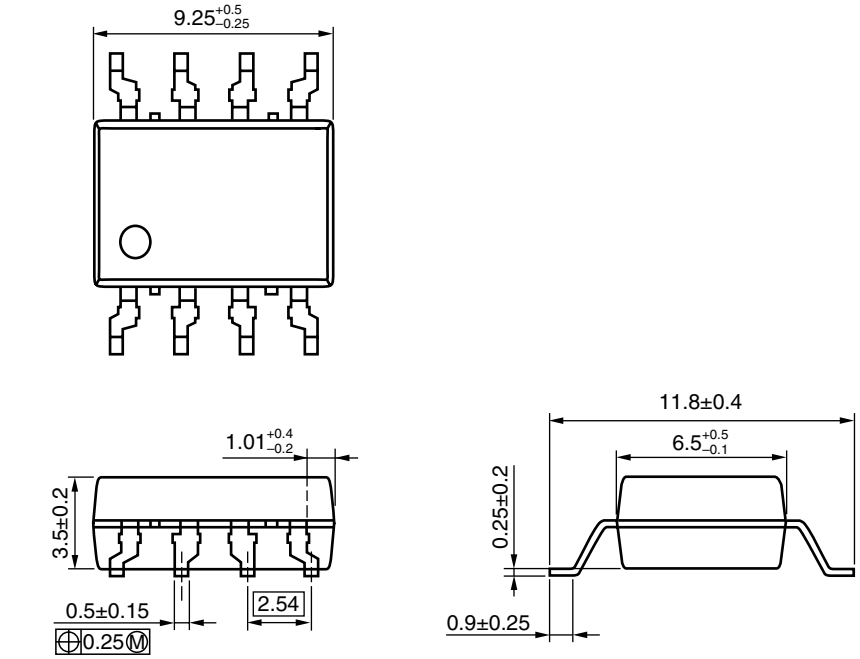
Lead Bending Type For Long Creepage Distance

PS8501L1



Lead Bending Type For Long Creepage Distance (Gull-wing) For Surface Mount

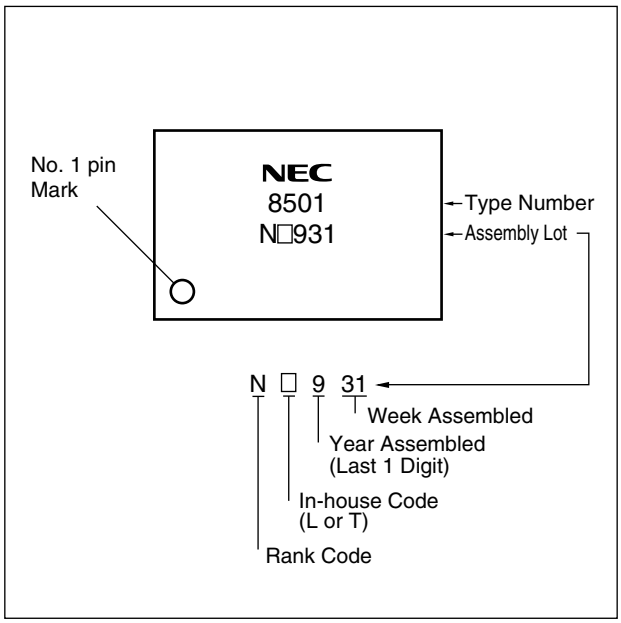
PS8501L2



PHOTOCOUPLER CONSTRUCTION

Parameter	PS8501, PS8501L3	PS8501L1, PS8501L2
Air Distance (MIN.)	7 mm	8 mm
Outer Creepage Distance (MIN.)	7 mm	8 mm
Isolation Distance (MIN.)	0.4 mm	0.4 mm

<R> **MARKING EXAMPLE**



ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number*1
PS8501	PS8501-AX	Pb-Free	Magazine case 50 pcs	Standard products	PS8501
PS8501L1	PS8501L1-AX	(Ni/Pd/Au)		(UL, CSA, BSI,	PS8501L1
PS8501L2	PS8501L2-AX			SEMKO, NEMKO,	PS8501L2
PS8501L3	PS8501L3-AX			DEMKO, FIMKO	PS8501L3
PS8501L2-E3	PS8501L2-E3-AX		Embossed Tape 1 000 pcs/reel	approved)	PS8501L2
PS8501L3-E3	PS8501L3-E3-AX				PS8501L3
PS8501-V	PS8501-V-AX		Magazine case 50 pcs	DIN EN60747-5-2	PS8501
PS8501L1-V	PS8501L1-V-AX			(VDE0884 Part2)	PS8501L1
PS8501L2-V	PS8501L2-V-AX			Approved (Option)	PS8501L2
PS8501L3-V	PS8501L3-V-AX				PS8501L3
PS8501L2-V-E3	PS8501L2-V-E3-AX		Embossed Tape 1 000 pcs/reel		PS8501L2
PS8501L3-V-E3	PS8501L3-V-E3-AX				PS8501L3

***1** For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current*1	I_F	25	mA
	Reverse Voltage	V_R	5	V
Detector	Supply Voltage	V_{CC}	35	V
	Output Voltage	V_O	35	V
	Output Current	I_O	8	mA
	Power Dissipation*2	P_C	100	mW
Isolation Voltage*3		BV	5 000	Vr.m.s.
Operating Ambient Temperature		T_A	–55 to +100	°C
Storage Temperature		T_{stg}	–55 to +125	°C

***1** Reduced to 0.33 mA/°C at T_A = 70°C or more.

***2** Reduced to 2.0 mW/°C at T_A = 75°C or more.

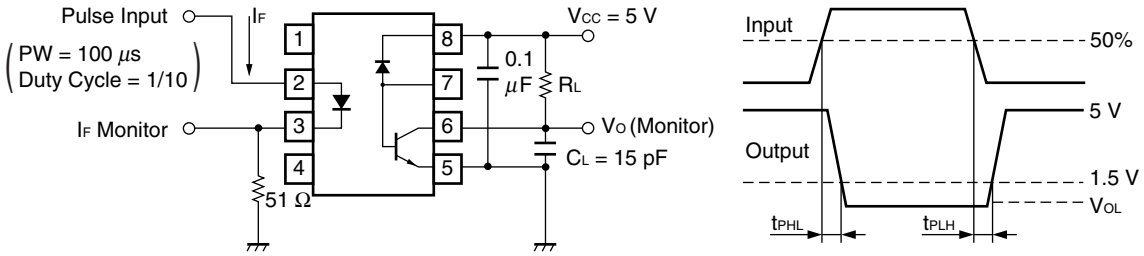
***3** AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output.
Pins 1-4 shorted together, 5-8 shorted together.

ELECTRICAL CHARACTERISTICS (T_A = 25°C)

Parameter		Symbol	Conditions	MIN.	TYP.*1	MAX.	Unit
Diode	Forward Voltage	V_F	I_F = 16 mA		1.7	2.2	V
	Reverse Current	I_R	V_R = 3 V			10	μA
	Forward Voltage Temperature Coefficent	$\Delta V_F/\Delta T_A$	I_F = 16 mA		–2.1		mV/°C
<R>	Terminal Capacitance	C_t	V = 0 V, f = 1 MHz		30		pF
Detector	High Level Output Current	I_{OH} (1)	I_F = 0 mA, V_{CC} = V_O = 5.5 V		3	500	nA
	High Level Output Current	I_{OH} (2)	I_F = 0 mA, V_{CC} = V_O = 35 V			100	μA
	Low Level Output Voltage	V_{OL}	I_F = 16 mA, V_{CC} = 4.5 V, I_O = 2.4 mA		0.15	0.4	V
	Low Level Supply Current	I_{CCL}	I_F = 16 mA, V_O = Open, V_{CC} = 35 V		150		μA
	High Level Supply Current	I_{CCH}	I_F = 0 mA, V_O = Open, V_{CC} = 35 V		0.01	1	μA
	DC Current Gain	h_{FE}	V_O = 5 V, I_O = 3 mA		65		
Coupled	Current Transfer Ratio	CTR	I_F = 16 mA, V_{CC} = 4.5 V, V_O = 0.4 V	15			%
	Isolation Resistance	R_{I-O}	V_{I-O} = 1 kV_{DC}	10^{11}			Ω
	Isolation Capacitance	C_{I-O}	V = 0 V, f = 1 MHz		0.7		pF
	Propagation Delay Time (H → L)*2	t_{PHL}	I_F = 16 mA, V_{CC} = 5 V, R_L = 1.9 kΩ		0.22	0.8	μs
	Propagation Delay Time (L → H)*2	t_{PLH}	I_F = 16 mA, V_{CC} = 5 V, R_L = 1.9 kΩ		0.35	0.8	μs

***1** Typical values at T_A = 25°C

***2** Test circuit for propagation delay time



Remark C_L includes probe and stray wiring capacitance.

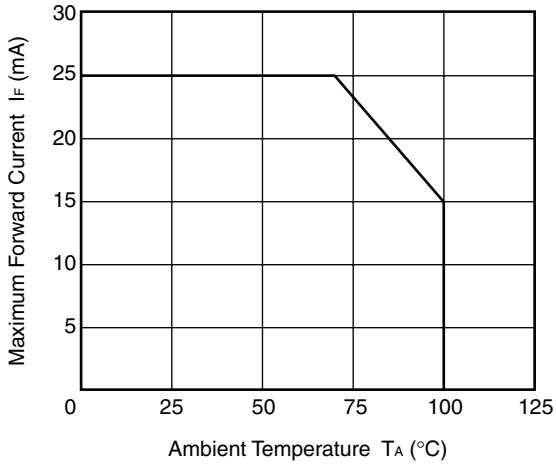
USAGE CAUTIONS

1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
2. By-pass capacitor of more than 0.1 μF is used between V_{CC} and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm.
3. <R> Pins 1, 4 (which is an NC*1 pin) can either be connected directly to the GND pin on the LED side or left open. Unconnected pins should not be used as a bypass for signals or for any other similar purpose because this may degrade the internal noise environment of the device.

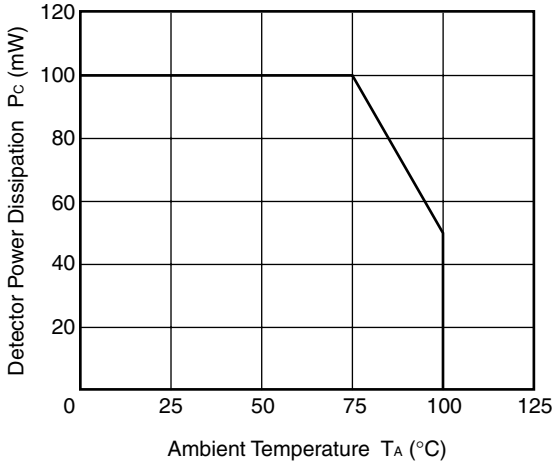
   ***1** NC: Non-Connection (No Connection)
4. Avoid storage at a high temperature and high humidity.

<R> **TYPICAL CHARACTERISTICS (T_A = 25°C, unless otherwise specified)**

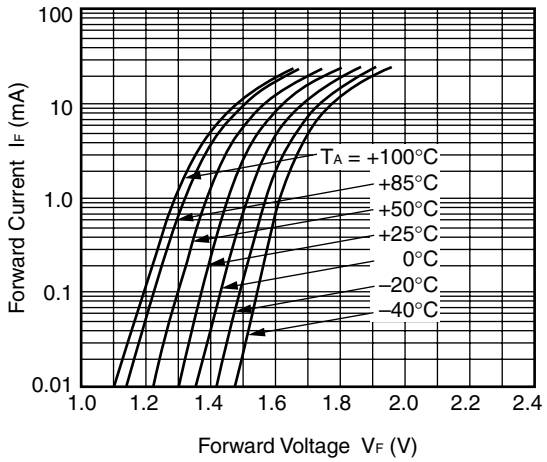
MAXIMUM FORWARD CURRENT vs. AMBIENT TEMPERATURE



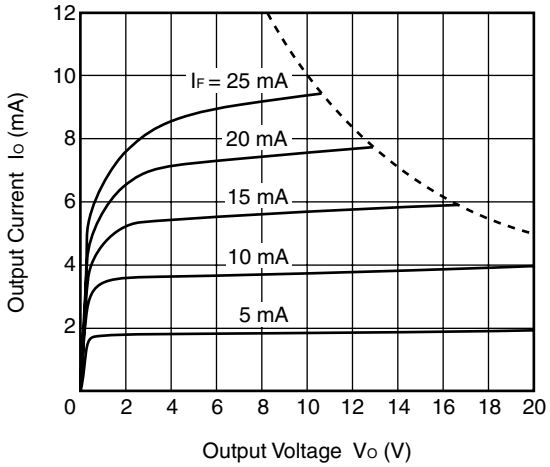
DETECTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



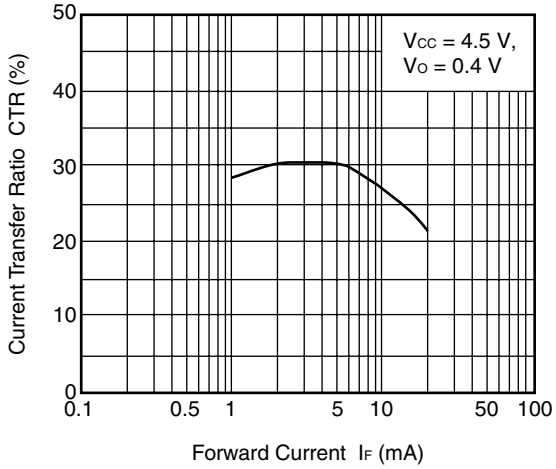
FORWARD CURRENT vs. FORWARD VOLTAGE



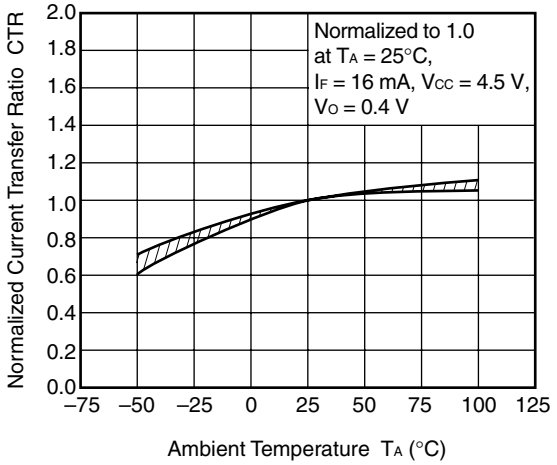
OUTPUT CURRENT vs. OUTPUT VOLTAGE



CURRENT TRANSFER RATIO vs. FORWARD CURRENT

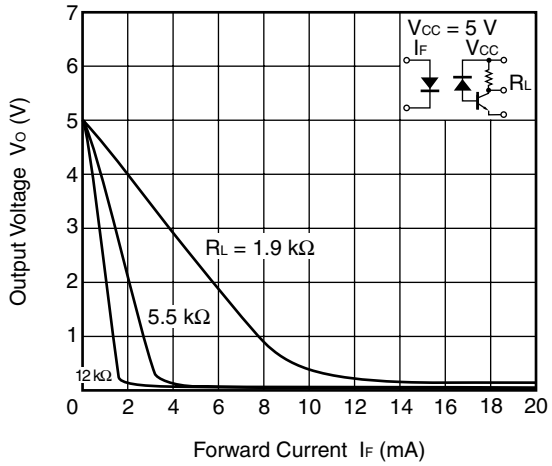


NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE

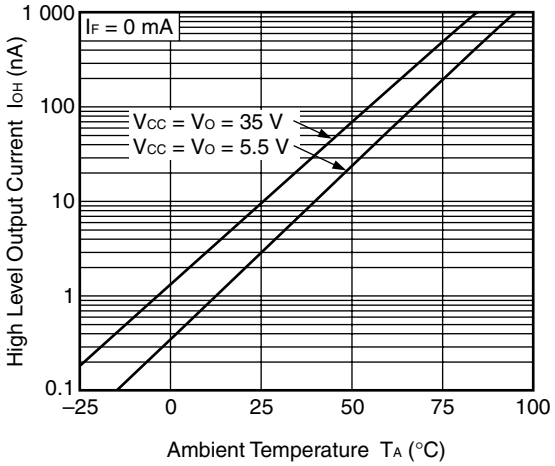


Remark The graphs indicate nominal characteristics.

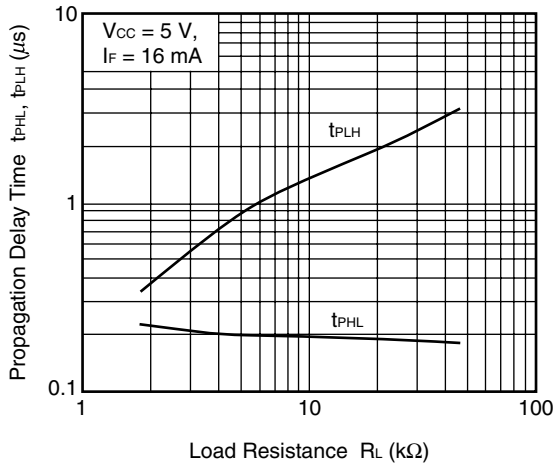
OUTPUT VOLTAGE vs.
FORWARD CURRENT



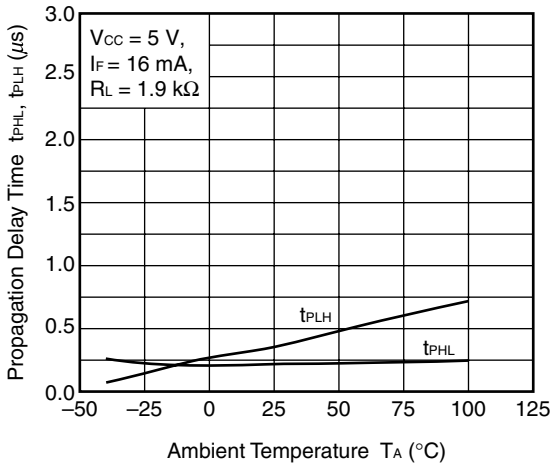
HIGH LEVEL OUTPUT CURRENT
vs. AMBIENT TEMPERATURE



PROPAGATION DELAY TIME,
vs. LORD RESISTANCE



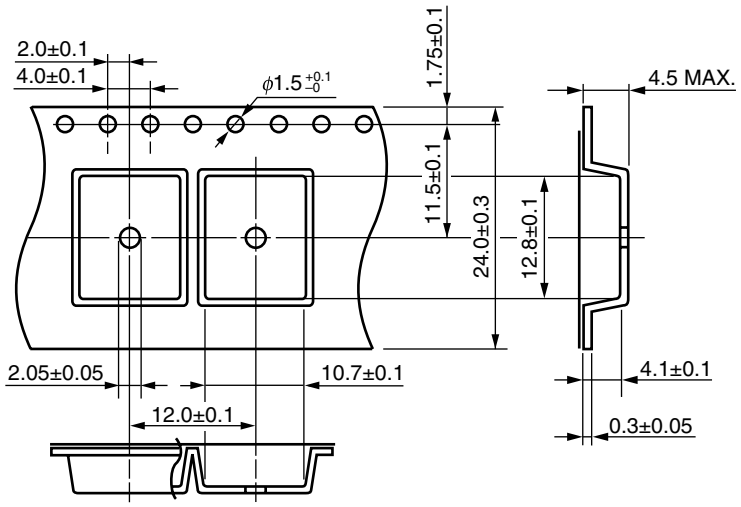
PROPAGATION DELAY TIME,
vs. AMBIENT TEMPERATURE



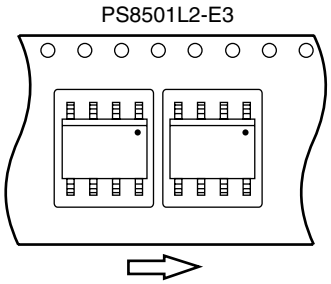
Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT: mm)

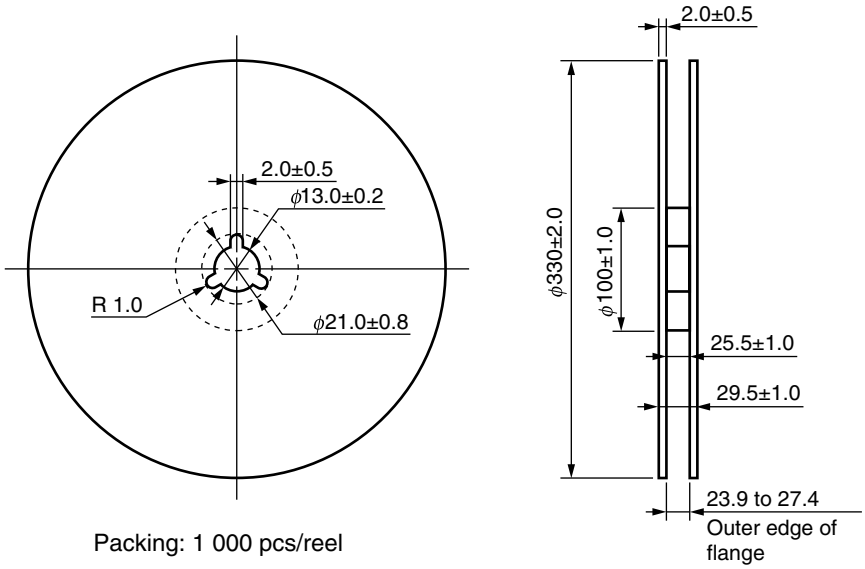
Outline and Dimensions (Tape)



Tape Direction

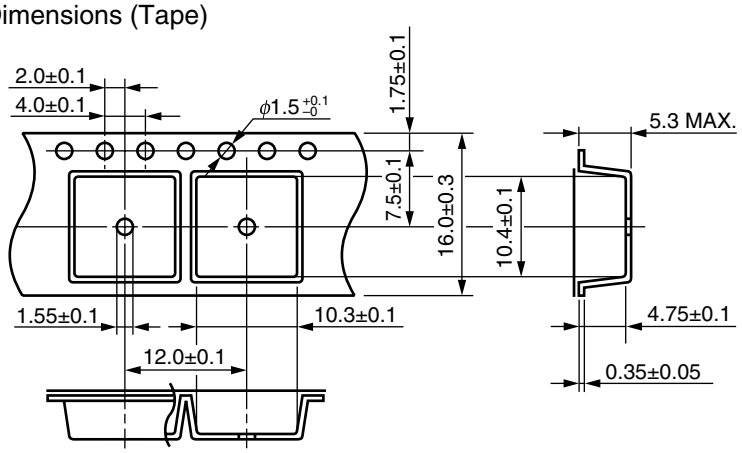


Outline and Dimensions (Reel)



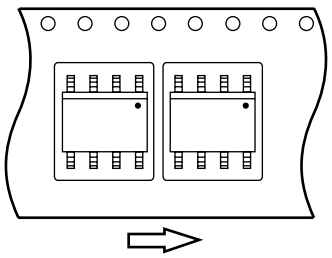
Packing: 1 000 pcs/reel

Outline and Dimensions (Tape)

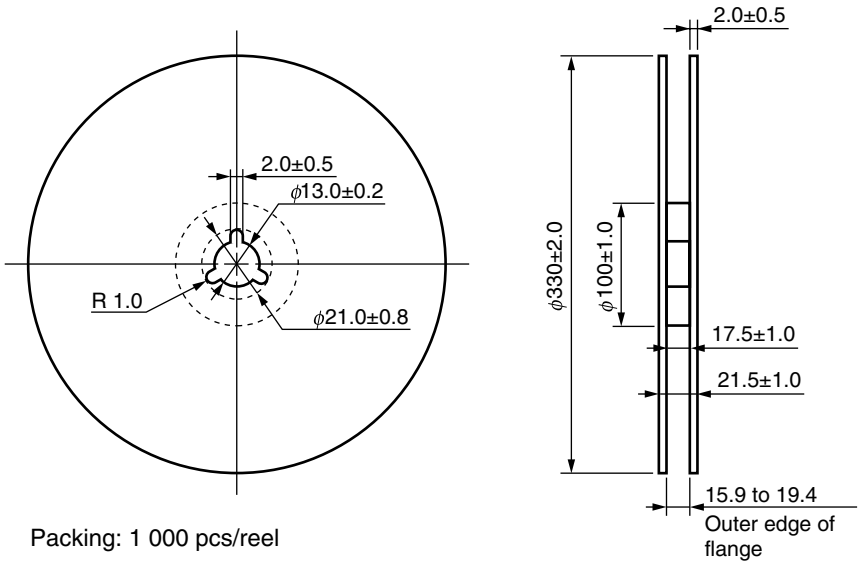


Tape Direction

PS8501L3-E3

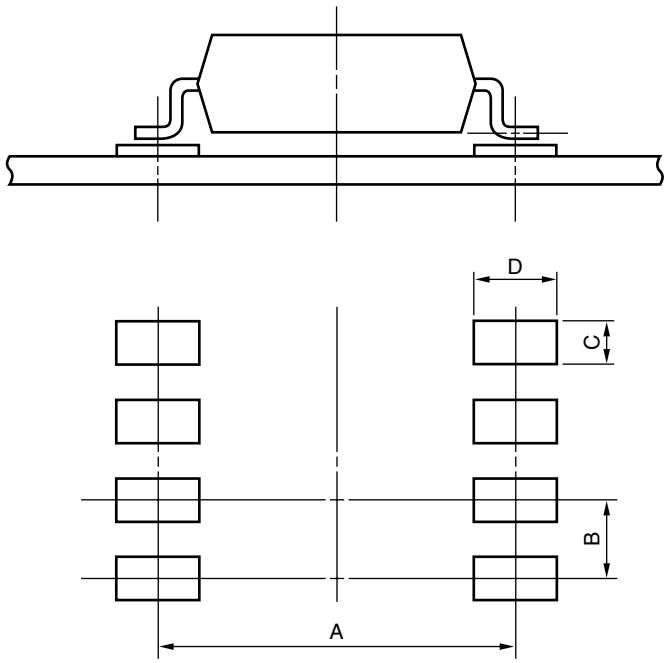


Outline and Dimensions (Reel)



Packing: 1 000 pcs/reel

RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



Part Number	Lead Bending	A	B	C	D
PS8501L2	lead bending type (Gull-wing) for long creepage distance (surface mount)	10.2	2.54	1.7	2.2
PS8501L3	lead bending type (Gull-wing) for surface mount	8.2	2.54	1.7	2.2

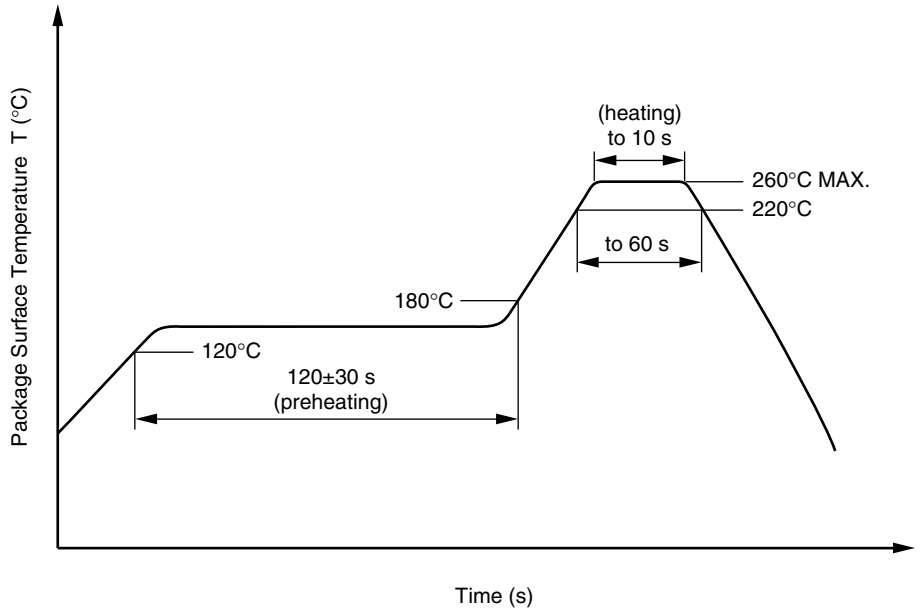
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

• Peak reflow temperature	260°C or below (package surface temperature)
• Time of peak reflow temperature	10 seconds or less
• Time of temperature higher than 220°C	60 seconds or less
• Time to preheat temperature from 120 to 180°C	120±30 s
• Number of reflows	Three
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

• Temperature	260°C or below (molten solder temperature)
• Time	10 seconds or less
• Preheating conditions	120°C or below (package surface temperature)
• Number of times	One (Allowed to be dipped in solder including plastic mold portion.)
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by soldering iron

• Peak temperature (lead part temperature)	350°C or below
• Time (each pins)	3 seconds or less
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

• Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between V_{CC}-emitters at startup, the output side may enter the on state, even if the voltage is within the absolute maximum ratings.

<R> SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Speck	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		55/100/21	
Dielectric strength maximum operating isolation voltage Test voltage (partial discharge test, procedure a for type test and random test) $U_{pr} = 1.5 \times U_{IORM}$, $P_d < 5$ pC	 U_{IORM} U_{pr}	 1 130 1 695	 V_{peak} V_{peak}
Test voltage (partial discharge test, procedure b for all devices) $U_{pr} = 1.875 \times U_{IORM}$, $P_d < 5$ pC	U_{pr}	2 119	V_{peak}
Highest permissible overvoltage	U_{TR}	8 000	V_{peak}
Degree of pollution (DIN EN 60664-1 VDE0110 Part 1)		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303 Part 11))	CTI	175	
Material group (DIN EN 60664-1 VDE0110 Part 1)		III a	
Storage temperature range	T_{stg}	–55 to +125	°C
Operating temperature range	T_A	–55 to +100	°C
Isolation resistance, minimum value V_{IO} = 500 V dc at T_A = 25°C V_{IO} = 500 V dc at T_A MAX. at least 100°C	 Ris MIN. Ris MIN.	 10^{12} 10^{11}	 Ω Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve) Package temperature Current (input current I_F, Psi = 0) Power (output or total power dissipation) Isolation resistance V_{IO} = 500 V dc at T_A = Tsi	 Tsi Isi Psi Ris MIN.	 175 400 700 10^{9}	 °C mA mW Ω

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To our customers,

Old Company Name in Catalogs and Other Documents

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Renesas Electronics website: http://www.renesas.com

April 1st, 2010
Renesas Electronics Corporation

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